

MAGNETIC IMPEDANCE ELEMENT EXCELLENT AGAINST THERMAL SHOCK AND MECHANICAL VIBRATION AND MAGNETIC IMPEDANCE SENSOR

Patent Number: JP2000081471
Publication date: 2000-03-21
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Requested Patent: JP2000081471
Application Number: JP19980338022 19981127
Priority Number(s):
IPC Classification: G01R33/02; B23K1/00; H01F1/153; H01L43/00; H01R4/02
EC Classification:
Equivalents:

Abstract

PROBLEM TO BE SOLVED: To provide an amorphous wire magnetic impedance(MI) element allowing easy junction such as solder joint.

SOLUTION: A MI element 1 has an amorphous wire 11 and metal solder 12 formed on two surface parts of the amorphous wire 11 which are spaced apart at a predetermined interval. This MI sensor has a base part, having a placement surface and conducting parts located in positions across the placement surface, and the amorphous wire supported at its center part on the placement surface and joined to each conducting part via the metal solder formed on the surface parts leading to the center part. Since the metal solder is applied to the surface parts, wettability is so well that firm welding with other metals is made possible with the use of the solder or the like. Thus, a junction resistant to mechanical vibration and thermal distortion such as temperature cycles is obtained.

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